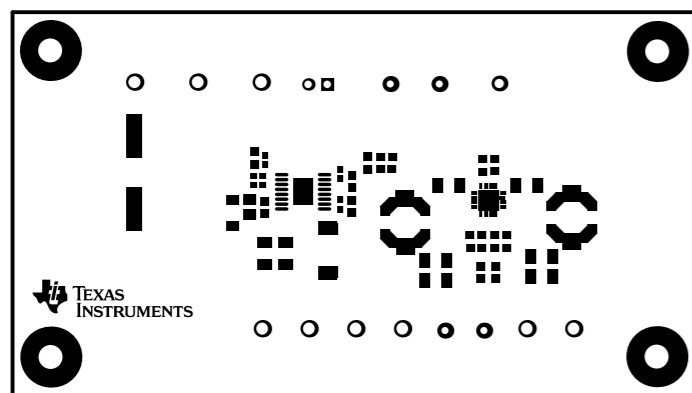
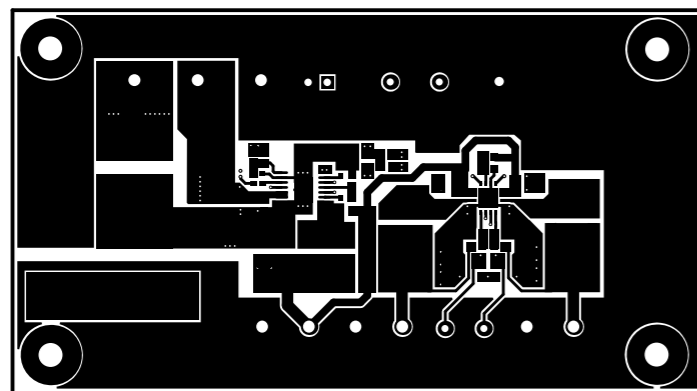


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/3/2014 4:00:04 PM	TEXAS INSTRUMENTS	

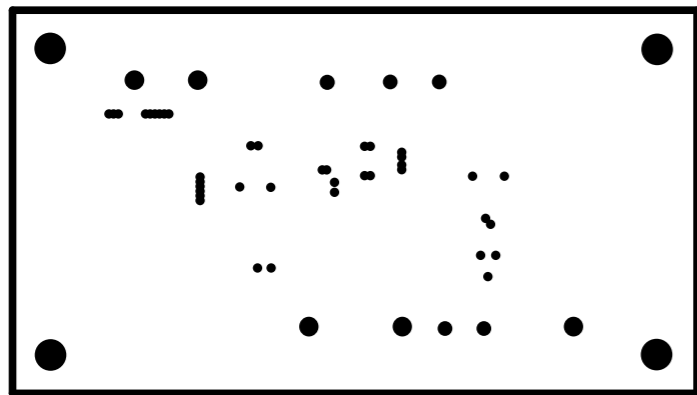


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/3/2014	4:00:05 PM	TEXAS INSTRUMENTS

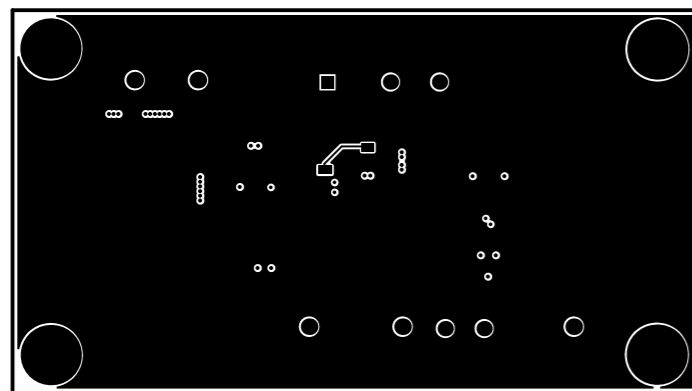
Layer Stack Up Detail for: PMP9462 R2.PcbDoc			
Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(<.GTS)		Solder Resist
Top Layer	(<.GTL)	1.4mil	FR-4
InternalPlane1	(<.GPI)	1.4mil	FR-4
MidLayer1	(<.GI)	1.4mil	FR-4
Bottom Layer	(<.GBL)	1.4mil	FR-4
Bottom Solder Mask	(<.GBS)		Solder Resist



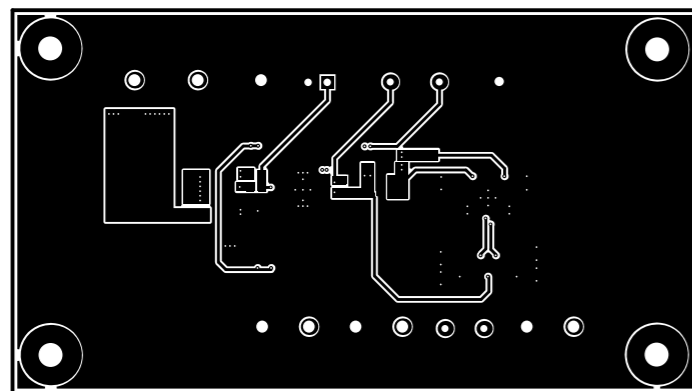
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/3/2014	4:00:06 PM	TEXAS INSTRUMENTS



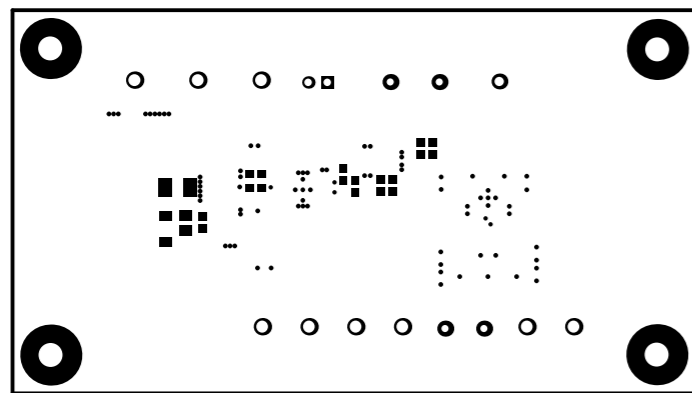
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Plane 1	GENERATED : 7/3/2014 4:00:07 PM	TEXAS INSTRUMENTS	



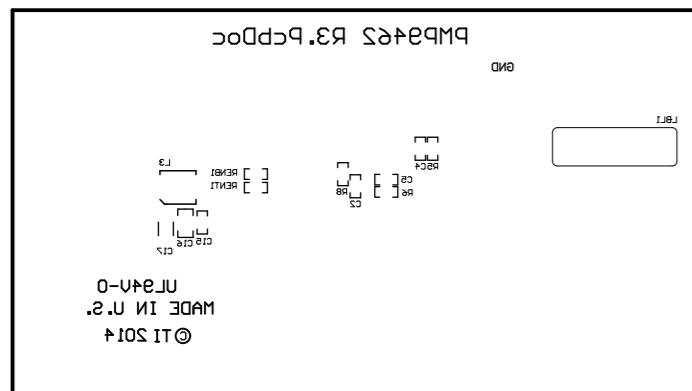
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M1 Board Outline			
PLOT NAME = Mid Layer 1	GENERATED : 7/3/2014 4:00:07 PM	TEXAS INSTRUMENTS	



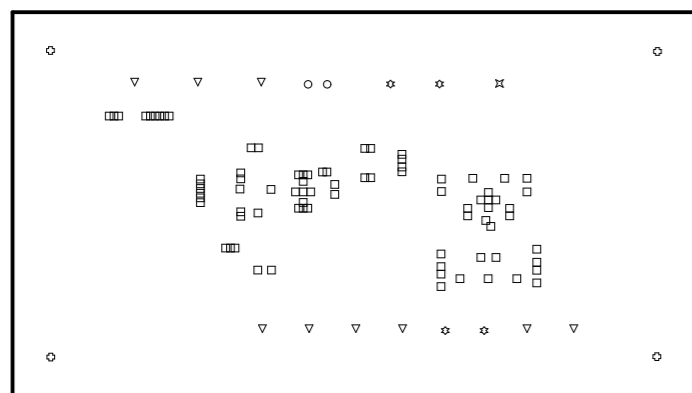
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/3/2014 4:00:08 PM	TEXAS INSTRUMENTS	



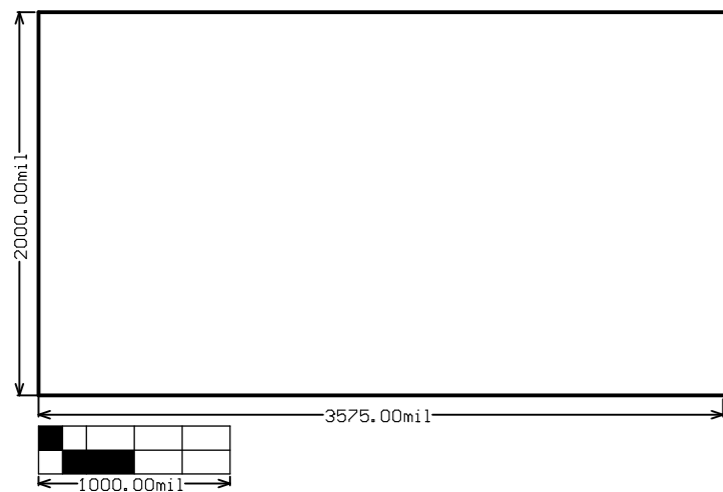
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/3/2014 4:00:09 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/3/2014	4:00:09 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/3/2014	4:00:10 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/3/2014 4:00:11 PM	TEXAS INSTRUMENTS	

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